SUBMINIATURE SOLID STATE LAMP

AM2520SYCK08

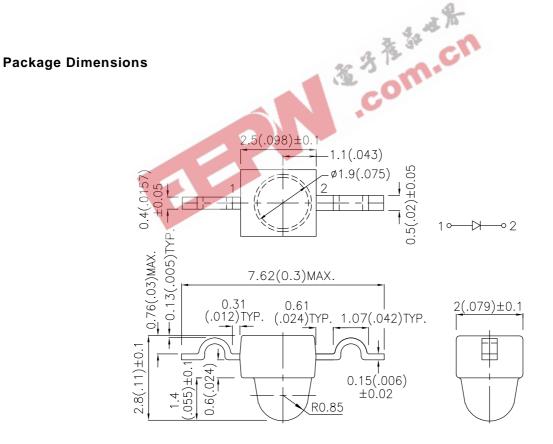
SUPER BRIGHT YELLOW

Features

- •SUBMINIATURE PACKAGE.
- •WIDE VIEWING ANGLE.
- ●YOKE LEAD.
- •LONG LIFE SOLID STATE RELIABILITY.
- •LOW PACKAGE PROFILE.
- ●PACKAGE: 1000PCS / REEL.
- •RoHS COMPLIANT.

Description

The Super Bright Yellow source color devices are made with DH InGaAIP on GaAs substrate Light Emitting Diode.



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.

 3. Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.

SPEC NO: DSAD1273 APPROVED: J. Lu

REV NO: V.2 CHECKED: Allen Liu DATE: MAR/05/2005 DRAWN: W.J.ZHU

PAGE: 1 OF 4 ERP:1202000719

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20mA		Viewing Angle
		,,	Min.	Тур.	201/2
AM2520SYCK08	SUPER BRIGHT YELLOW (InGaAIP)	WATER CLEAR	70	300	20°

Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Yellow	590		nm	IF=20mA
λD	Dominant Wavelength	Super Bright Yellow	590	3	nm	Ir=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Yellow	20	34	nm	IF=20mA
С	Capacitance	Super Bright Yellow	20	3	pF	VF=0V;f=1MHz
VF	Forward Voltage	Super Bright Yellow	2.0	2.5	V	IF=20mA
lr	Reverse Current	Super Bright Yellow	C	10	uA	VR = 5V

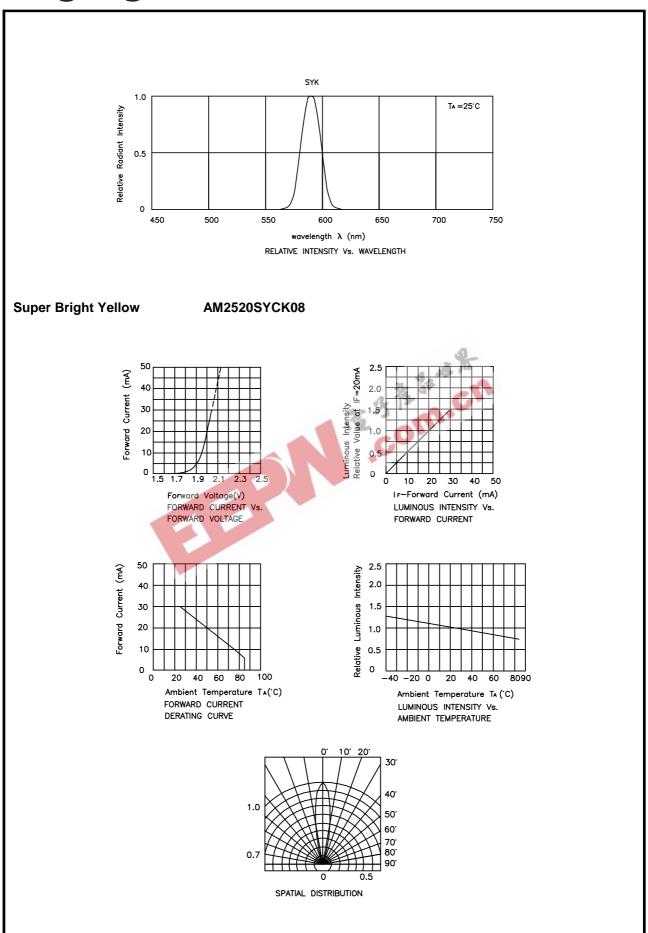
Absolute Maximum Ratings at Ta=25°C

Parameter	Super Bright Yellow	Units
Power dissipation	125	mW
DC Forward Current	30	mA
Peak Forward Current [1]	175	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

SPEC NO: DSAD1273 **REV NO: V.2** DATE: MAR/05/2005 PAGE: 2 OF 4 APPROVED: J. Lu **CHECKED: Allen Liu** DRAWN: W.J.ZHU ERP:1202000719

Note: 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

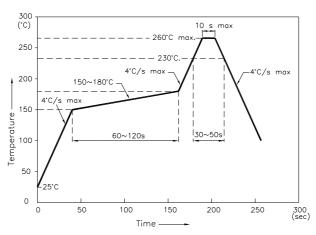


 SPEC NO: DSAD1273
 REV NO: V.2
 DATE: MAR/05/2005
 PAGE: 3 OF 4

 APPROVED: J. Lu
 CHECKED: Allen Liu
 DRAWN: W.J.ZHU
 ERP:1202000719

AM2520SYCK08

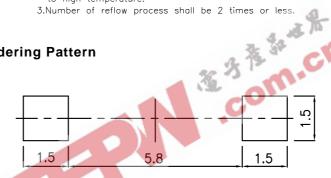
Reflow Soldering Profile For Lead-free SMT Process.



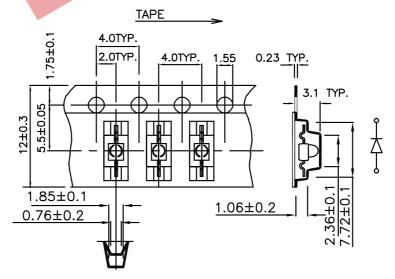
- NOTES:

 1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it $\,$ is exposed
 - to high temperature. 3. Number of reflow process shall be 2 times or less

Recommended Soldering Pattern (Units: mm)



Tape Specifications (Units: mm)



Remarks:

If there is sorting requirement (eg. forward voltage, luminous intensity or wavelength), the condition as follows:

- 1. Wavelength: +/-1nm (Test condition is based on the sorting standard).
- 2.Luminous intensity: +/-15% (Test condition is based on the sorting standard).
- 3. Forward voltage: +/-0.1V (Test condition is based on the sorting standard).

SPEC NO: DSAD1273 **REV NO: V.2** DATE: MAR/05/2005 PAGE: 4 OF 4 APPROVED: J. Lu **CHECKED: Allen Liu** DRAWN: W.J.ZHU ERP:1202000719